

Product Summary

BV_{DSS}	$R_{DS(ON)} \text{ Max}$	I_D $T_c = +25^\circ\text{C}$
60V	27m Ω @ $V_{GS} = 10\text{V}$	22.6A
	30m Ω @ $V_{GS} = 6\text{V}$	21.5A

Description and Applications

This MOSFET is designed to meet the stringent requirements of Automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

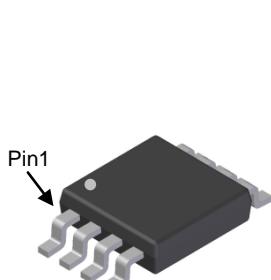
- Engine Management Systems
- Body Control Electronics
- DC-DC Converters

Features and Benefits

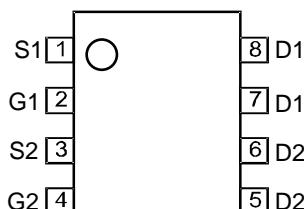
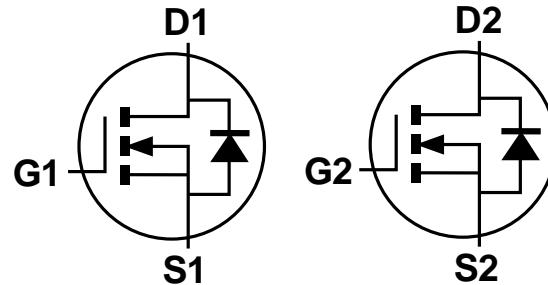
- Rated to +175°C – Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching – Ensures More Reliable and Robust End Application
- Low $R_{DS(ON)}$ – Minimizes Power Losses
- Low Q_g – Minimizes Switching Losses
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- **PPAP Capable (Note 4)**

Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish – Matte Tin Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.074 grams (Approximate)



SO-8


 Top View
 Pin Configuration


Equivalent Circuit

Ordering Information (Note 5)

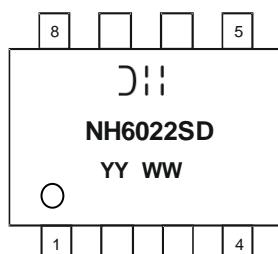
Part Number	Case	Packaging
DMNH6022SSDQ-13	SO-8	2,500 / Tape & Reel

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to http://www.diodes.com/product_compliance_definitions.html.
5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information

SO-8



DII = Manufacturer's Marking
 NH6022SD = Product Type Marking Code
 YYWW = Date Code Marking
 YY = Year (ex: 16 = 2016)
 WW = Week (01 to 53)

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	60	V
Gate-Source Voltage	V_{GSS}	± 20	V
Continuous Drain Current $V_{GS} = 10\text{V}$ (Note 7)	$T_C = +25^\circ\text{C}$	I_D	22.6
	$T_C = +100^\circ\text{C}$		16.0
Pulsed Drain Current (10 μs pulse, duty cycle = 1%)	$T_A = +25^\circ\text{C}$	I_D	7.1
	$T_A = +70^\circ\text{C}$		5.9
Maximum Continuous Body Diode Forward Current (Note 7)	I_{DM}	45	A
Avalanche Current $L = 0.1\text{mL}$ (Note 8)	I_{AS}	22	A
Avalanche Energy $L = 0.1\text{mL}$ (Note 8)	E_{AS}	24	mJ

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 6)	$T_A = +25^\circ\text{C}$	P_D	1.5 W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	104 $^\circ\text{C}/\text{W}$
	$t < 10\text{s}$		60
Total Power Dissipation (Note 7)	$T_A = +25^\circ\text{C}$	P_D	2.1 W
Thermal Resistance, Junction to Ambient (Note 7)	Steady State	$R_{\theta JA}$	74 $^\circ\text{C}/\text{W}$
	$t < 10\text{s}$		42
Thermal Resistance, Junction to Case (Note 7)	$R_{\theta JC}$	7.25	
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +175	$^\circ\text{C}$

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 9)						
Drain-Source Breakdown Voltage	BV_{DSS}	60	—	—	V	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$
Zero Gate Voltage Drain Current $T_J = +25^\circ\text{C}$	I_{DSS}	—	—	1	μA	$V_{DS} = 60\text{V}, V_{GS} = 0\text{V}$
Gate-Source Leakage	I_{GSS}	—	—	± 100	nA	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$
ON CHARACTERISTICS (Note 9)						
Gate Threshold Voltage	$V_{GS(\text{TH})}$	1.0	—	3.0	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
Static Drain-Source On-Resistance	$R_{DS(\text{ON})}$	—	21	27	$\text{m}\Omega$	$V_{GS} = 10\text{V}, I_D = 5\text{A}$
			24	30		$V_{GS} = 6\text{V}, I_D = 5\text{A}$
Diode Forward Voltage	V_{SD}	—	0.8	1.2	V	$V_{GS} = 0\text{V}, I_S = 1.7\text{A}$
DYNAMIC CHARACTERISTICS (Note 10)						
Input Capacitance	C_{iss}	—	2127	—	pF	$V_{DS} = 25\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$
Output Capacitance	C_{oss}	—	86	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	54	—	pF	
Gate Resistance	R_g	—	2.0	—	Ω	$V_{DS} = 0\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$
Total Gate Charge at ($V_{GS} = 10\text{V}$)	Q_g	—	32	—	nC	$V_{DS} = 30\text{V}, I_D = 6\text{A}$
Total Gate Charge at ($V_{GS} = 4.5\text{V}$)	Q_g	—	14	—	nC	
Gate-Source Charge	Q_{gs}	—	7	—	nC	
Gate-Drain Charge	Q_{gd}	—	4	—	nC	
Turn-On Delay Time	$t_{D(\text{ON})}$	—	5.4	—	ns	$V_{GS} = 10\text{V}, V_{DS} = 30\text{V}, R_G = 6\Omega, I_D = 1\text{A}$
Turn-On Rise Time	t_R	—	4.4	—	ns	
Turn-Off Delay Time	$t_{D(\text{OFF})}$	—	30.4	—	ns	
Turn-Off Fall Time	t_F	—	8.4	—	ns	
Body Diode Reverse Recovery Time	t_{RR}	—	18.1	—	ns	$I_F = 1.7\text{A}, \text{di}/\text{dt} = 100\text{A}/\mu\text{s}$
Body Diode Reverse Recovery Charge	Q_{RR}	—	12.5	—	nC	$I_F = 1.7\text{A}, \text{di}/\text{dt} = 100\text{A}/\mu\text{s}$

Notes: 6. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

7. Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate.

8. I_{AS} and E_{AS} rating are based on low frequency and duty cycles to keep $T_J = +25^\circ\text{C}$.

9. Short duration pulse test used to minimize self-heating effect.

10. Guaranteed by design. Not subject to product testing.

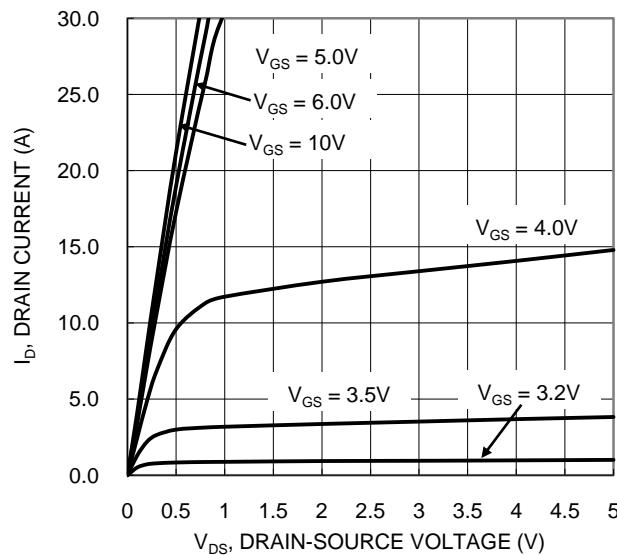


Figure 1. Typical Output Characteristic

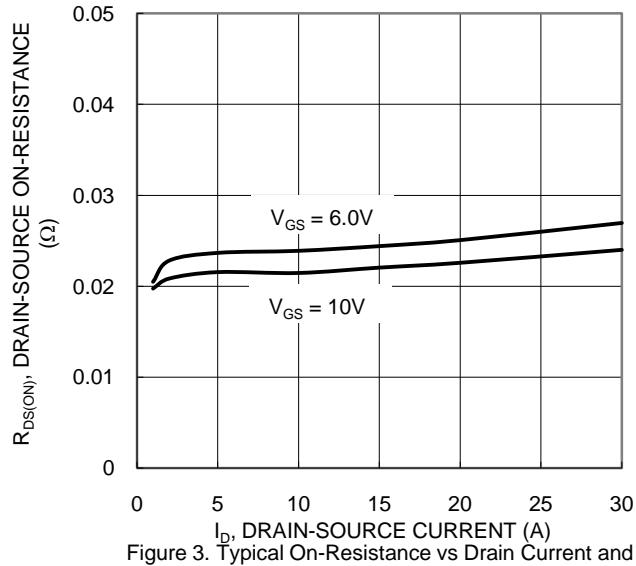


Figure 3. Typical On-Resistance vs Drain Current and Gate Voltage

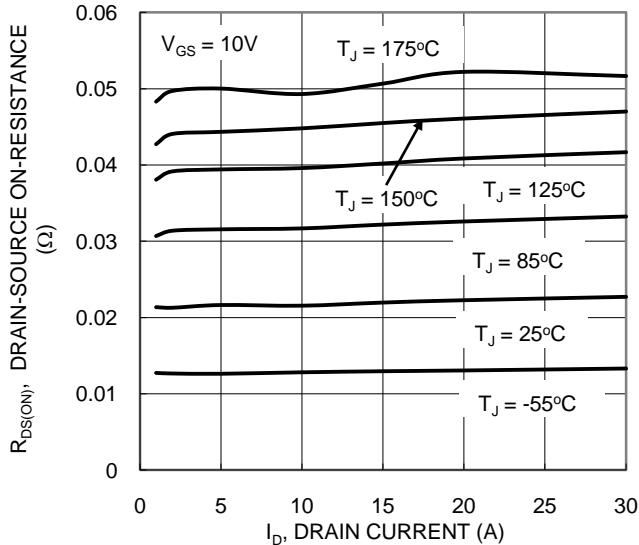


Figure 5. Typical On-Resistance vs Drain Current and Junction Temperature

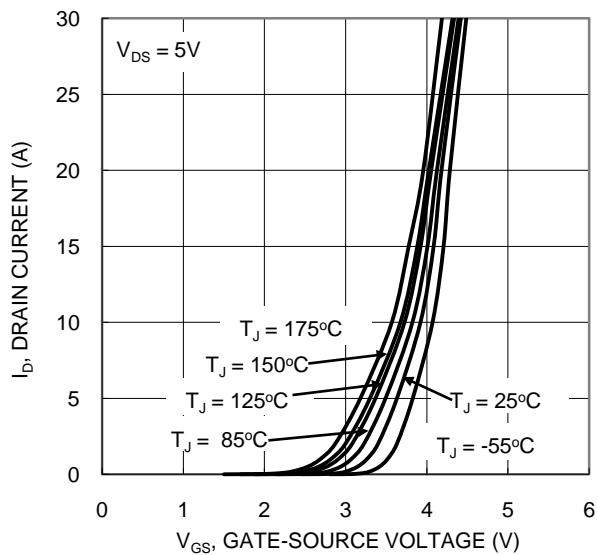


Figure 2. Typical Transfer Characteristic

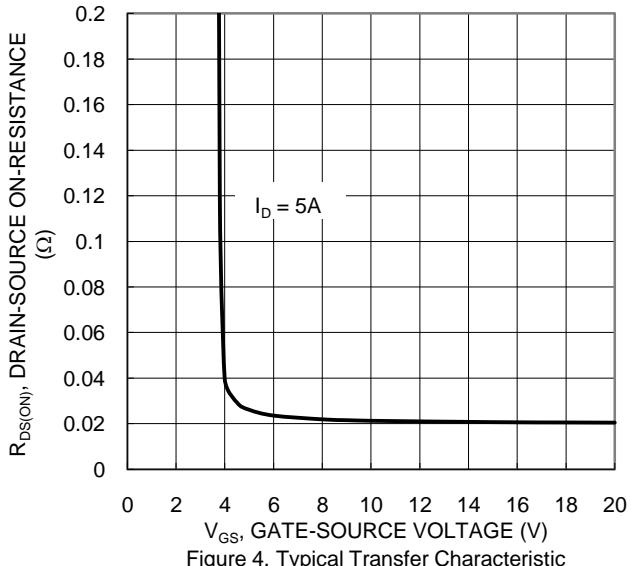


Figure 4. Typical Transfer Characteristic

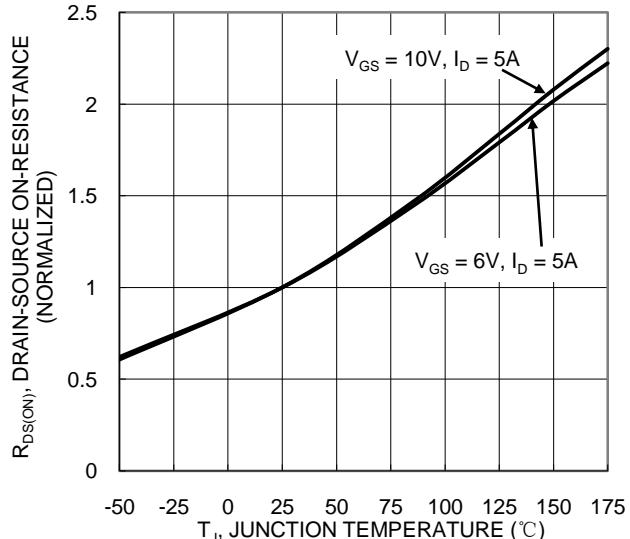


Figure 6. On-Resistance Variation with Junction Temperature

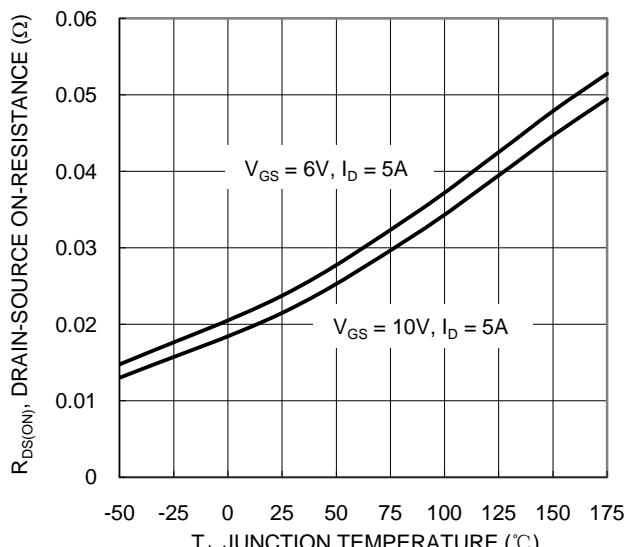


Figure 7. On-Resistance Variation with Junction Temperature

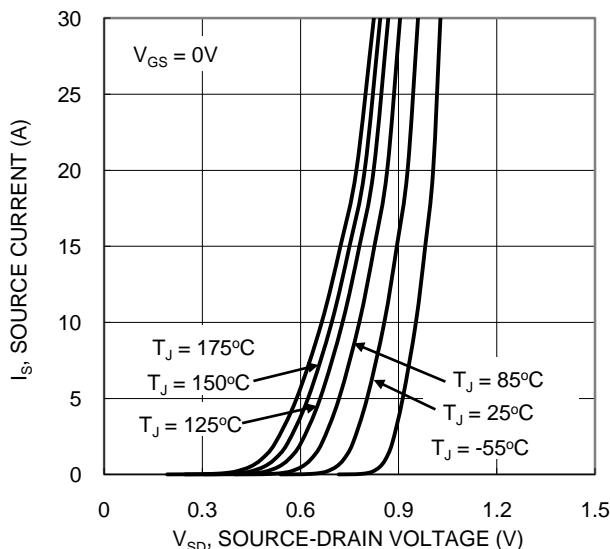


Figure 9. Diode Forward Voltage vs Current

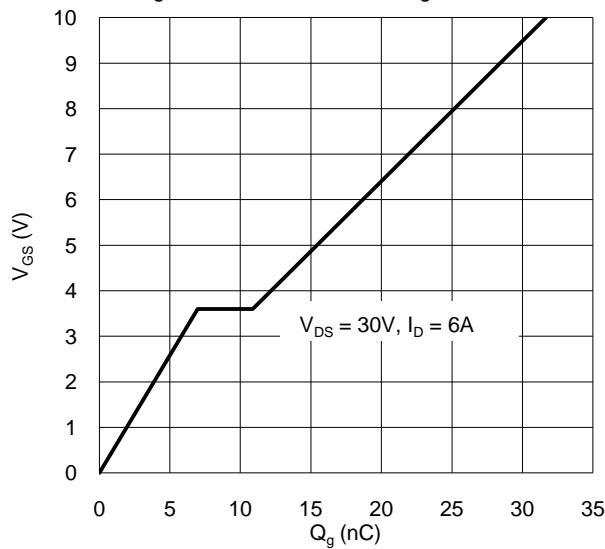


Figure 11. Gate Charge

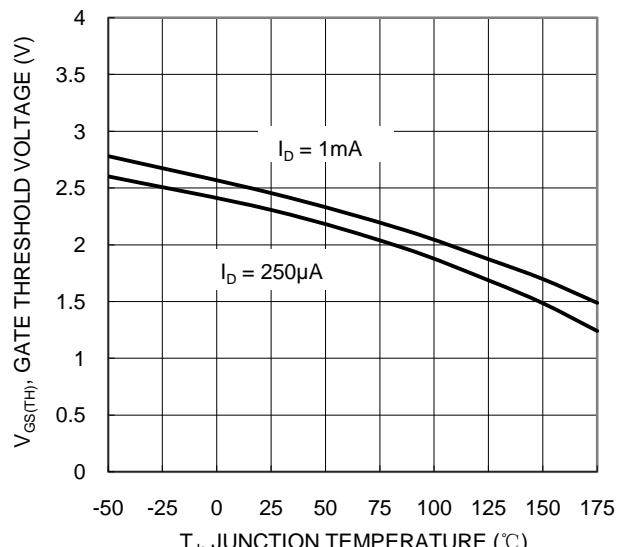


Figure 8. Gate Threshold Variation vs Junction Temperature

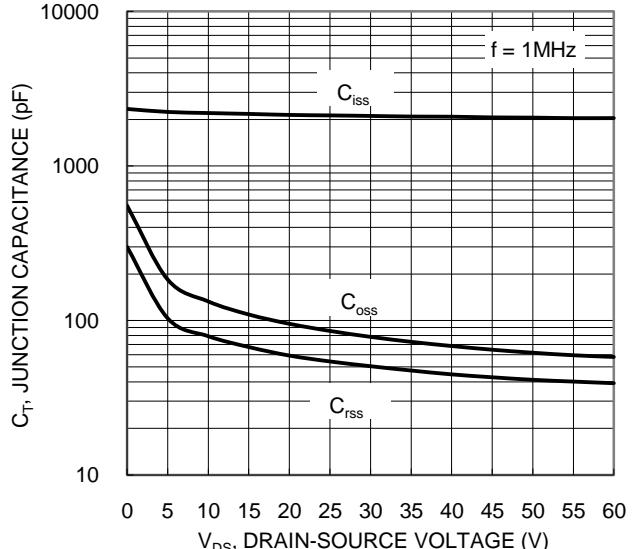


Figure 10. Typical Junction Capacitance

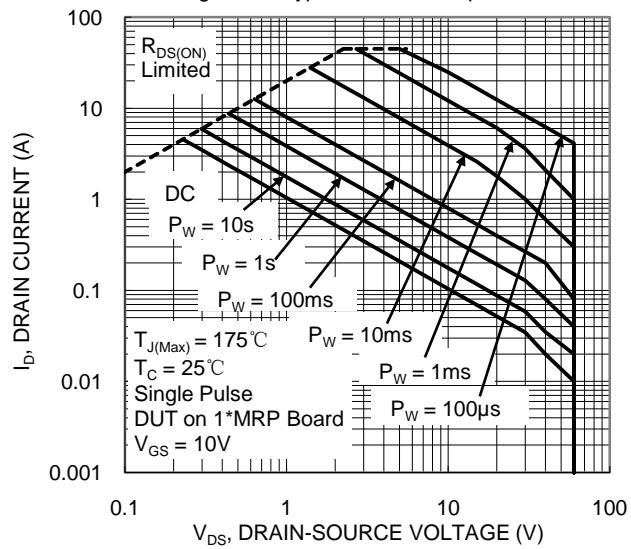


Figure 12. SOA, Safe Operation Area

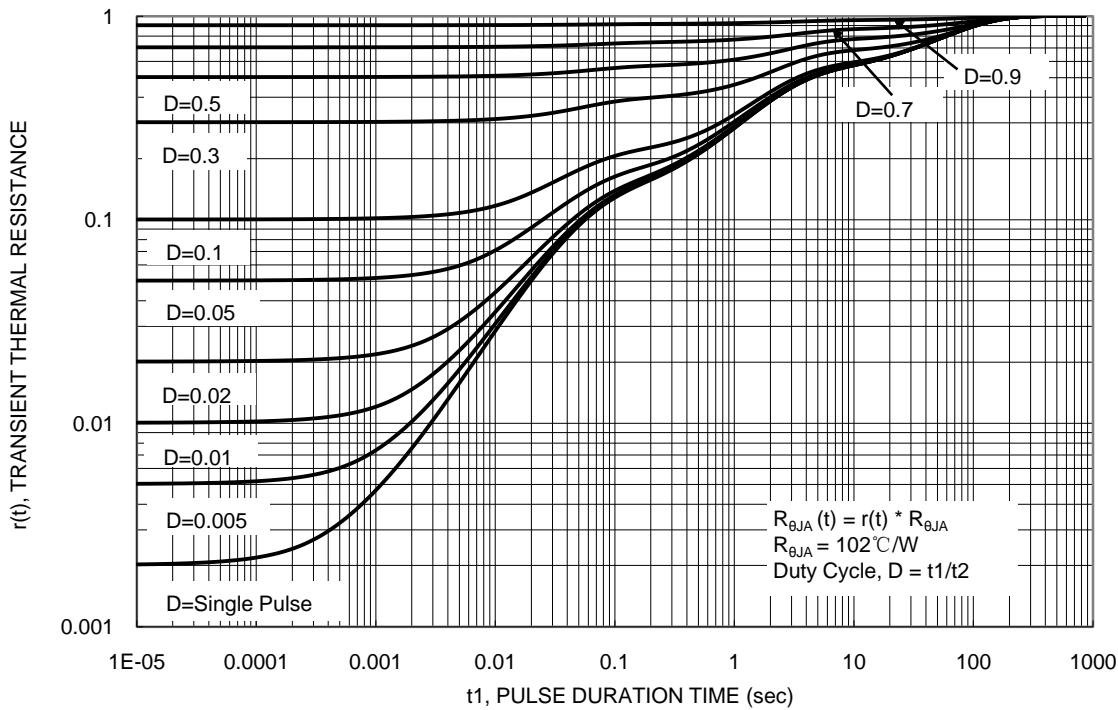
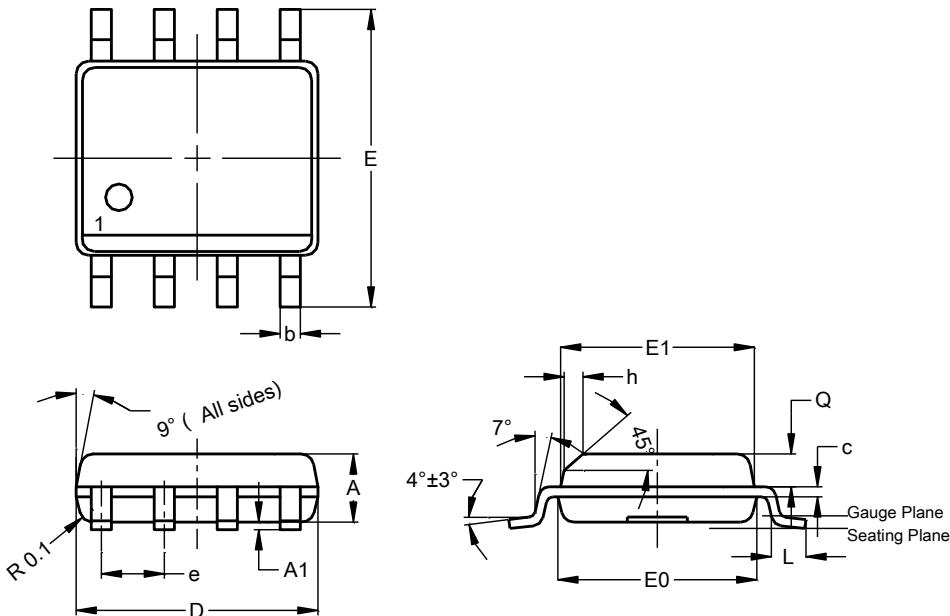


Figure 13. Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SO-8



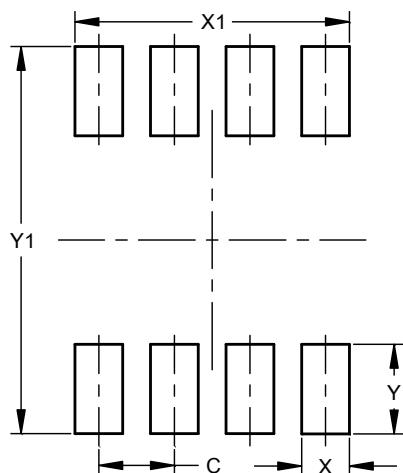
SO-8			
Dim	Min	Max	Typ
A	1.40	1.50	1.45
A1	0.10	0.20	0.15
b	0.30	0.50	0.40
c	0.15	0.25	0.20
D	4.85	4.95	4.90
E	5.90	6.10	6.00
E1	3.80	3.90	3.85
E0	3.85	3.95	3.90
e	--	--	1.27
h	-	--	0.35
L	0.62	0.82	0.72
Q	0.60	0.70	0.65

All Dimensions in mm

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SO-8



Dimensions	Value (in mm)
C	1.27
X	0.802
X1	4.612
Y	1.505
Y1	6.50

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